

L Number	Hits	Search Text	DB	Time stamp
1	1242	("235/492").CCLS.	USPAT; US-PGPUB	2001/11/16 15:33
3	146	gem\$1plus.as.	USPAT; US-PGPUB	2001/11/16 15:01
4	112	gem\$1plus.as. not (("235/492").CCLS.)	USPAT; US-PGPUB	2001/11/16 15:26
5	47	mini adj2 card	USPAT; US-PGPUB	2001/11/16 15:30
6	5311	card same substrate\$1	USPAT; US-PGPUB	2001/11/16 15:33
7	389990	mold\$4	USPAT; US-PGPUB	2001/11/16 15:30
9	24	(card same substrate\$1) same mold\$4 and (("235/492").CCLS.)	USPAT; US-PGPUB	2001/11/16 15:31
10	352	("235/492").CCLS.	EPO; JPO; DERWENT; IBM TDB	2001/11/16 15:33
11	6109	card same substrate\$1	EPO; JPO; DERWENT; IBM TDB	2001/11/16 15:34
12	18	((("235/492").CCLS.) and (card same substrate\$1)	EPO; JPO; DERWENT; IBM TDB	2001/11/16 15:36
13	427	("235/441").CCLS.	USPAT; US-PGPUB	2001/11/16 15:41
14	21	"mini card"	EPO; JPO; DERWENT; IBM TDB	2001/11/16 15:41
15	24	hitachi.in.	USPAT; US-PGPUB	2001/11/16 15:45
16	10090	(chip ic (integrated adj1 circuit) smart) adj2 card	USPAT; US-PGPUB	2001/11/16 16:00
17	321	mold\$4 same ((chip ic (integrated adj1 circuit) smart) adj2 card)	USPAT; US-PGPUB	2001/11/16 15:52
21	100	(mold\$4 same ((chip ic (integrated adj1 circuit) smart) adj2 card)) and substrate\$1	USPAT; US-PGPUB	2001/11/16 15:53
22	60	((mold\$4 same ((chip ic (integrated adj1 circuit) smart) adj2 card)) and substrate\$1) and memory	USPAT; US-PGPUB	2001/11/16 15:54
23	27222	(chip ic (integrated adj1 circuit) smart) adj2 card	EPO; JPO; DERWENT; IBM TDB	2001/11/16 16:01
24	401	((chip ic (integrated adj1 circuit) smart) adj2 card) same mold\$4	EPO; JPO; DERWENT; IBM TDB	2001/11/16 16:01
26	2	((((chip ic (integrated adj1 circuit) smart) adj2 card) same mold\$4) same substrate\$1) and memory	EPO; JPO; DERWENT; IBM TDB	2001/11/16 16:01
25	93	((((chip ic (integrated adj1 circuit) smart) adj2 card) same mold\$4) same substrate\$1	EPO; JPO; DERWENT; IBM TDB	2001/11/16 16:02